



Initial Product/Process Change Notification

Document #: IPCN26836X1

Issue Date: 29 Nov 2025

Title of Change:	Update to IPCN26836X - Assembly and Test Site Transfer with BOM and Tester Changes for SC-70 Package at Tarlac, Philippines
Proposed First Ship date:	12 Jun 2026 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact
Marking of Parts/ Traceability of Change:	Changed material can be identified by date code/lot code and site code
Change Category:	Test Change, Assembly Change
Change Sub-Category(s):	Material Change, Manufacturing Site Transfer

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Tarlac, Philippines	None

Description and Purpose:

This IPCN26836X1 is an update to IPCN26836X due to a change in the product case outline. onsemi wishes to inform customers of its plan to qualify onsemi Tarlac, Philippines as the new Assembly and Test site for the SC-70 package.

The change involves transferring the assembly and test site from AUK, Korea to onsemi Tarlac, Philippines, along with changes to the Bill of Materials, tester platform, and product case outline.

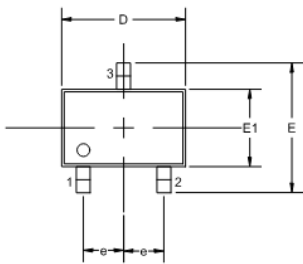
	Before Change Description	After Change Description
Assembly Site	AUK, Korea	onsemi Tarlac, Philippines
Test Site	AUK, Korea	onsemi Tarlac, Philippines
Bond Wire	1.0 mil Au	1.0 mil Pd-coated Cu
Mold Compound	Kyocera KTMC1050G	Hysol GR640
Plating	Sn	Sn
Tester	KDN KT-95-DS	Powertech QT6166E
Case Outline	419AB	419

There is no product marking change as a result of this change.

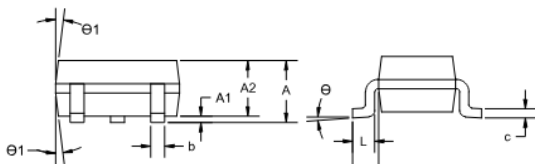
onsemi would also like to inform customers of the intent to change from case outline 419AB to 419 for the SC-70 products listed in this notification.

Before Change

Case Outline: 419AB



TOP VIEW



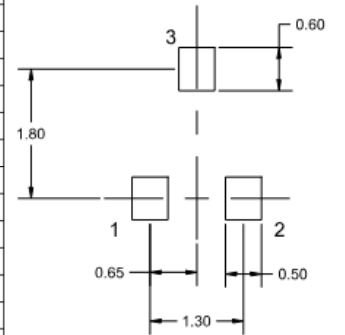
SIDE VIEW

END VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES IN DEGREES.
2. COMPLIES WITH JEDEC MO-203

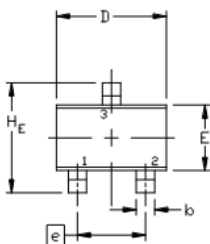
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.80		1.10
A1	0.00		0.10
A2	0.80	0.90	1.00
b	0.15		0.30
c	0.08		0.22
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
e	0.65 BSC		
L	0.26	0.36	0.46
L1	0.42 REF		
theta	0°		8°
theta1	4°		10°



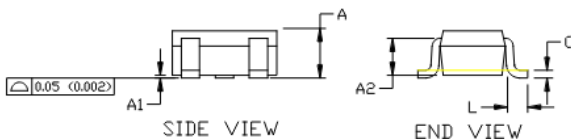
SOLDERING FOOTPRINT

After Change

Case Outline: 419



TOP VIEW



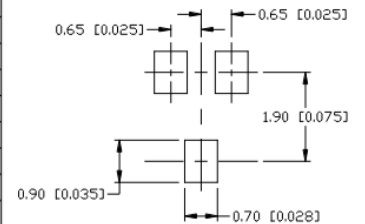
SIDE VIEW

END VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH

DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 BSC		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.00	2.20	0.071	0.080	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
HE	2.00	2.10	2.40	0.079	0.083	0.095



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SOLDERING FOOTPRINT

Qualification Plan:

QV DEVICE NAME: BSS138W

RMS: not yet available

PACKAGE: SC-70-3

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Ta= 150 °C, 100% max rated V	1008 hrs
High Temperature Gate Bias	JESD22-A108	Ta= 150 °C, 100% max rated V	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta = 150	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C, Pre IOL, TC, uHAST, HAST for surface mount pkgs only	
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only	
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimension	JESD22-B120	As per case outline	

Estimated date for qualification completion: **27 January 2026**

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
BSS138W	#NONE	BSS138W

Appendix A: Changed Products

PCN#: IPCN26836X1
Issue Date: Nov 29, 2025

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
BSS138W		BSS138W	#NONE	